

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.30037	100.0	3.2
			Subtotal	0.30037	100	3.2
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03764	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01129	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03764	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.55354	99.77	400.0777
			Subtotal	37.64011	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.85201	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.94169	10.0	63.3
	Filler	Silica fused	60676-86-0	50.5044	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11883	0.2	1.266
			Subtotal	59.41693	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.34664	100.0	25
			Subtotal	2.34664	100	25
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.014	100.0	0.1491
	Pure metal	Aluminium (Al)	7429-90-5	0.04727	100.0	0.50364
			Subtotal	0.06127	200	0.65274
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00469	2.0	0.05
	Lead alloy	Silver (Ag)	7440-22-4	0.00587	2.5	0.0625
	Lead alloy	Lead (Pb)	7439-92-1	0.2241	95.5	2.3875
			Subtotal	0.23466	100	2.5
			Total	99.99998	100	1065.35274

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